EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	11759	(leadframe or (lead adj frame) or foil) with (plastic adj (film or layer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 20:11
S2	2952	(leadframe or (lead adj frame) or foil) with (diode or photodiode)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 20:13
S3	12	S1 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 20:13
S4	6	@ad <= "20030604" and S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 20:49
S5	4	(("6523446") or ("5399416")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/16 20:53
S6	57309	(leadframe or (lead adj frame) or foil) with (multi-layer or multilayer or (multi adj layer) or laminate or laminated or multi-layered)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 21:13
S7	4235	S1 and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/16 21:14
S8	3118	@ad <= "20030604" and S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 21:15

S9	775	S8 and package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 21:17
S10	519034	(die or chip or component or IC or (integrated adj circuit) or (semiconductor adj device) or diode or photodiode) with (encapsulant or encapsulat$4 or sealant or seal$3 or mold$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 21:24
S11	141	S9 and S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 21:25
S12	141	S11 and (plastic adj (film or layer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 21:45
S13	43	(leadframe or (lead adj frame) or foil) with (plastic adj (film or layer)) with punch $4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/17 21:37
S14	39	@ad <= "20030604" and S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/17 21:38
S15	43	(leadframe or (lead adj frame) or foil) with (plastic adj (film or layer)) with punch $4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/17 21:40
S16	39	@ad <= "20030604" and S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/17 21:41
S17	4	("3781596").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/17 23:20

S18	2322	(multi-layer or (multi adj layer) or multilayer or laminat$3) with (leadframe or lead-frame or (lead adj frame))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/23 01:01
S19	1685	@ad <= "20030604" and S18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/23 01:02
S20	8322	(leadframe or lead-frame or (lead adj frame)) with (pattern$3 or opening or groove or recess or vias)	US-PGPUB; USPAT	OR	ON	2008/09/23 01:05
S21	361	S19 and S20	US-PGPUB; USPAT	OR	ON	2008/09/23 01:05
S22	210685	((multi-layer or (multi adj layer) or multilayer or laminat$3) or (leadframe or lead-frame or (lead adj frame))) with (plastic or ceramic or polymer or synthetic or semisynthetic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/23 01:08
S23	189	S21 and S22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/23 01:08
S24	13554	((257/786) or (257/784) or (257/734) or (257/736) or (257/666) or (257/667) or (257/668) or (257/669) or (257/676) or (257/672) or (257/675) or (257/676) or (257/677) or (257/690) or (257/701) or (257/713)).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/09/23 01:47

S25	532	S24 and ((multi-layer or (multi adj layer) or multilayer or laminat $3) with (leadframe or lead-frame or (lead adj frame) or frame))	US-PGPUB; USPAT	OR	ON	2008/09/23 01:48
S26	364	@ad <= "20030604" and S25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/23 01:49
S27	280	S26 not S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/23 01:49

10/14/08 4:21:16 AM
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